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1	BRS	L1	152	204/297.1.CCLS.	USPAT	2000/07/15 23:23
2	BRS	L2	11	brogden.inv.	USPAT	2000/07/15 23:24
3	BRS	L3	3785	contact adj assembly	USPAT	2000/07/15 23:24
4	BRS	L4	404672	sealing or seal	USPAT	2000/07/15 23:25
5	BRS	L5	101526 1	contact	USPAT	2000/07/15 23:27
6	IS&R	L6	4	((("5232511") or ("5168886") or ("5168887") or ("5078852"))).PN.	USPAT	2000/07/15 23:29
7	BRS	L7	995	3 and 4 and 5	USPAT	2000/07/15 23:29
8	BRS	L9	38861	204/\$.ccls.	USPAT	2000/07/15 23:30
9	BRS	L8	1	7 and 1	USPAT	2000/07/15 23:30
10	BRS	L10	24	9 and 7	USPAT	2000/07/15 23:45
11	BRS	L11	0	10 and bellows	USPAT	2000/07/15 23:48
12	IS&R	L12	1	("6001234").PN.	USPAT	2000/07/15 23:49
13	BRS	L13	1	12 and bellows	USPAT	2000/07/15 23:49

DOCUMENT-IDENTIFIER: US 6001234 A

TITLE: Methods for plating semiconductor workpieces using a
workpiece-engaging
electrode assembly with sealing boot

DWKU:

6001234

DEPR:

More specifically, and referring to FIG. 22, seal 868 can include
a rim portion

870 which engages workpiece surface W and forms a sealing contact
therebetween

when the finger assembly is moved to the engaged position. Such
seal

advantageously isolates finger electrode 860 from the processing
environment

and materials which may plate out or otherwise be encountered
therein. Seal

868 can be provided with an optional bellows wall structure 894
(FIG. 22), that

allows more axial flexibility of the seal.

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